



## 7A, 600V N-CHANNEL MOSFET

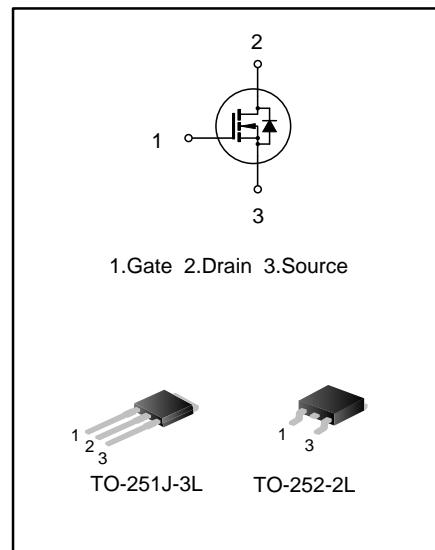
### GENERAL DESCRIPTION

SVFP7N60CMJ/D is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

### FEATURES

- 7A, 600V,  $R_{DS(on)(typ.)}=0.96\Omega @ V_{GS}=10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



### ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVFP7N60CMJ	TO-251J-3L	P7N60CMJ	Halogen free	Tube
SVFP7N60CDTR	TO-252-2L	P7N60CD	Halogen free	Tape&Reel



## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings		Unit
		SVFP7N60CMJ	SVFP7N60CD	
Drain-Source Voltage	V <sub>DS</sub>	600		V
Gate-Source Voltage	V <sub>GS</sub>	±30		V
Drain Current	T <sub>C</sub> =25°C	I <sub>D</sub>	7.0	A
	T <sub>C</sub> =100°C		4.4	
Drain Current Pulsed	I <sub>DM</sub>	28		A
Power Dissipation(T <sub>C</sub> =25°C) -Derate above 25°C	P <sub>D</sub>	93	90	W
		0.74	0.72	W/°C
Single Pulsed Avalanche Energy(Note 1)	E <sub>AS</sub>	490		mJ
Reverse Diode dv/dt (Note 2)	dv/dt	4.5		V/ns
MOSFET dv/dt Ruggedness (Note 3)	dv/dt	50		V/ns
Operation Junction Temperature Range	T <sub>J</sub>	-55~+150		°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150		°C

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVFP7N60CMJ	SVFP7N60CD	
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	1.34	1.39	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62	62.0	°C/W



## ELECTRICAL CHARACTERISTICS ( $T_J=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	600	--	--	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1.0	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	--	4.0	V
Static Drain- Source On State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3.5\text{A}$	--	0.96	1.2	$\Omega$
Input Capacitance	$R_g$	$f=1.0\text{MHz}$	--	5.0	--	$\Omega$
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	--	770	--	pF
Output Capacitance	$C_{\text{oss}}$		--	96	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	8.7	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}, I_{\text{D}}=7.0\text{A}, R_G=25\Omega$	--	16	--	ns
Turn-on Rise Time	$t_r$		--	33	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	52	--	
Turn-off Fall Time	$t_f$		--	32	--	
Total Gate Charge	$Q_g$	$V_{\text{DS}}=480\text{V}, I_{\text{D}}=7.0\text{A}, V_{\text{GS}}=10\text{V}$	--	21	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	4.5	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	10	--	

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

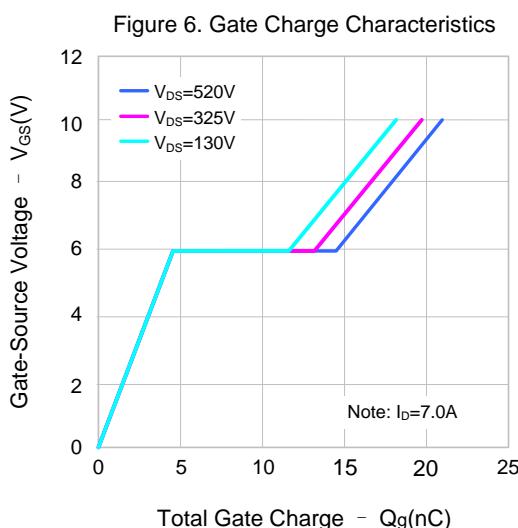
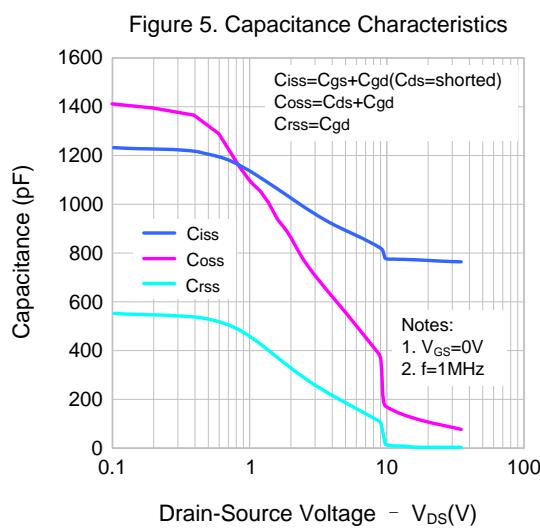
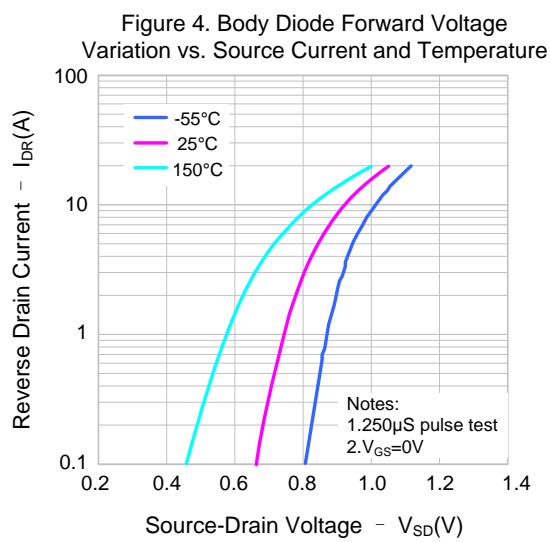
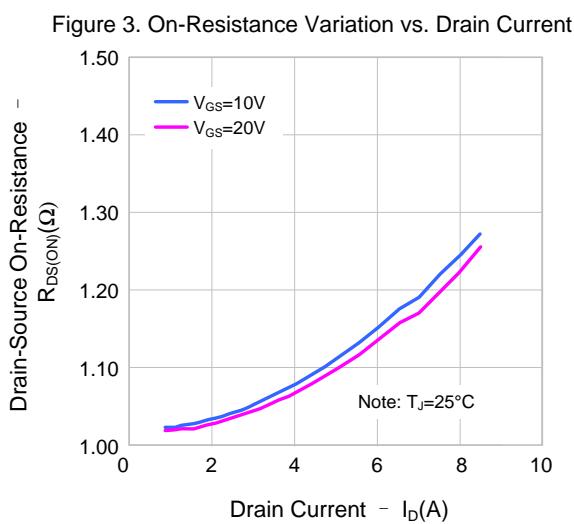
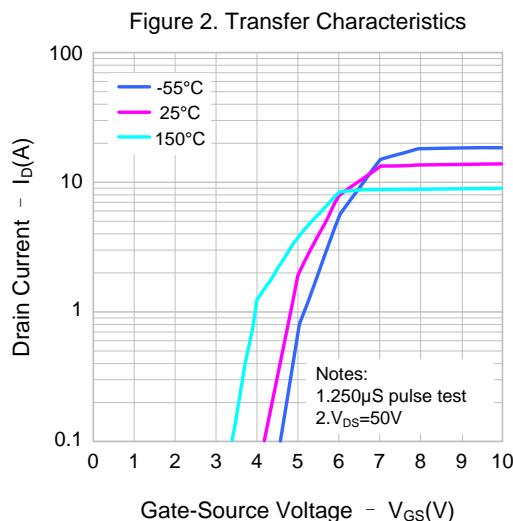
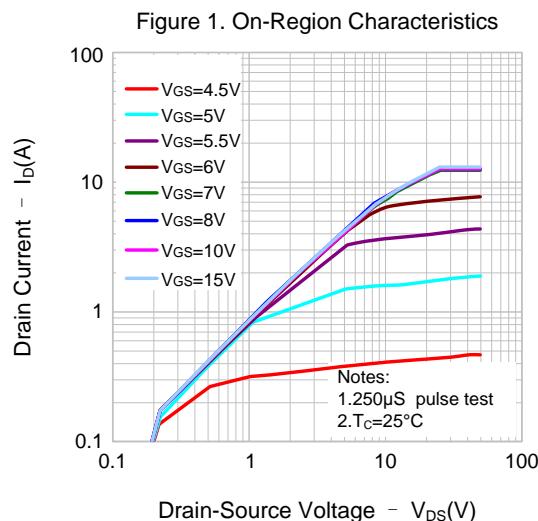
Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_s$	Integral Reverse P-N Junction Diode in the MOSFET	--	--	7.0	A
Pulsed Source Current	$I_{\text{SM}}$		--	--	28	
Diode Forward Voltage	$V_{\text{SD}}$	$I_s=7.0\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.4	V
Reverse Recovery Time	$T_{\text{rr}}$	$I_s=7.0\text{A}, V_{\text{GS}}=0\text{V}, \frac{dI_F}{dt}=100\text{A}/\mu\text{s}$	--	482	--	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		--	2.9	--	

### Notes:

1.  $L=30\text{mH}, I_{\text{AS}}=5.16\text{A}, V_{\text{DD}}=100\text{V}, R_G=25\Omega$ , starting temperature  $T_J=25^\circ\text{C}$ ;
2.  $V_{\text{DS}}=0\sim 400\text{V}, I_{\text{SD}}\leq 7\text{A}, T_J=25^\circ\text{C}$ ;
3.  $V_{\text{DS}}=0\sim 480\text{V}$ ;
4. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$ ;
5. Essentially independent of operating temperature.



## TYPICAL CHARACTERISTICS





## TYPICAL CHARACTERISTICS(CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

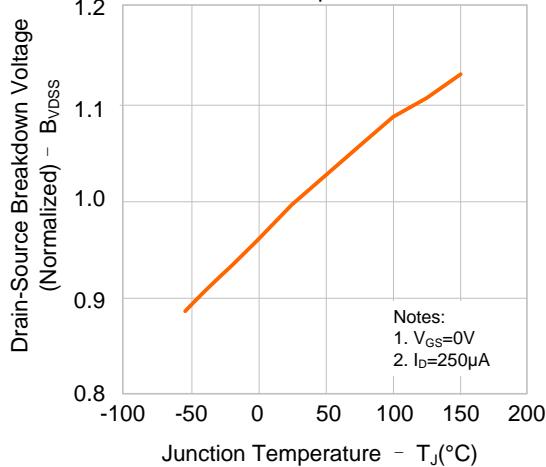


Figure 8. On-resistance vs. Temperature

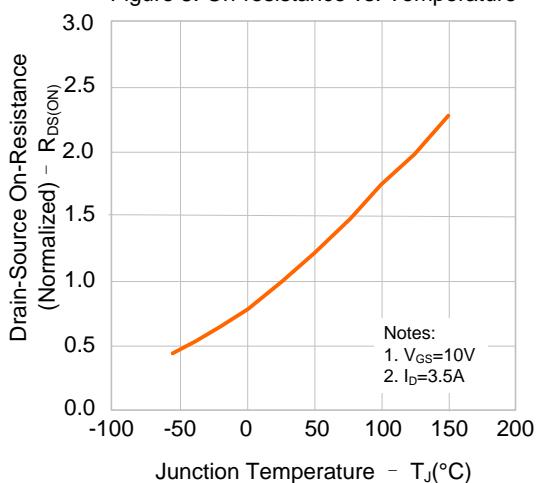


Figure 9-1. Max. Safe Operating Area (SVFP7N60CMJ)

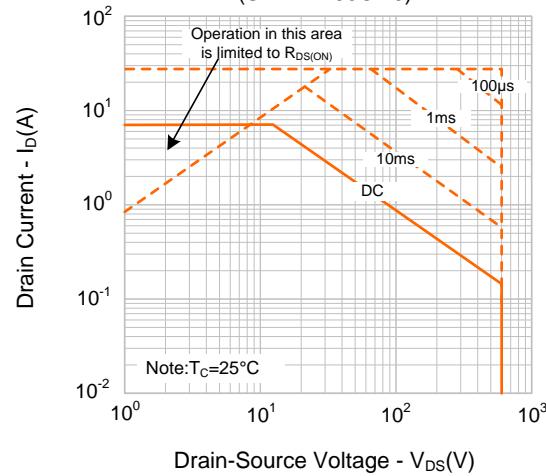


Figure 9-2. Max. Safe Operating Area (SVFP7N60CD)

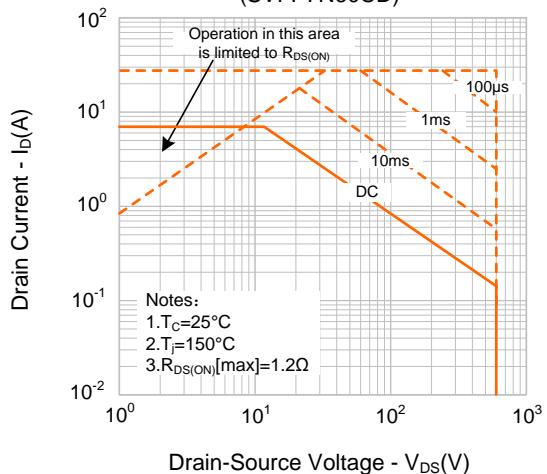
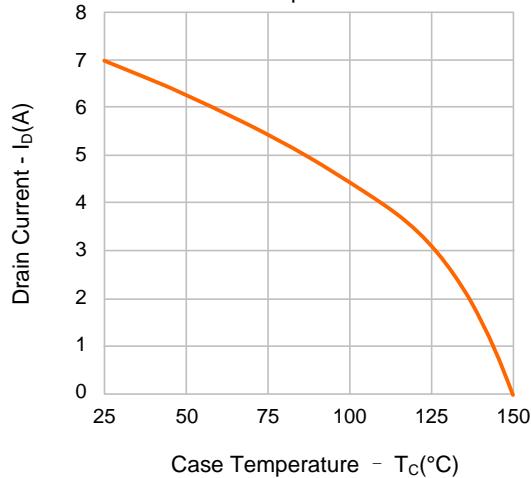
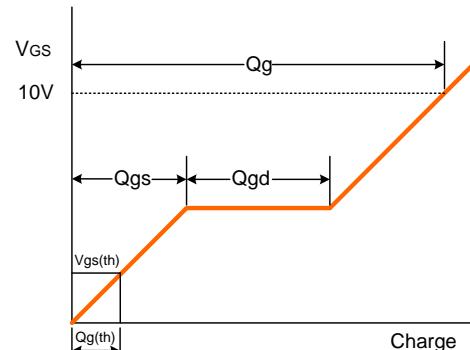
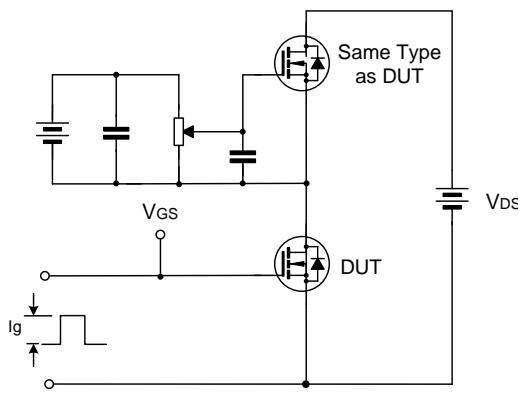


Figure 10. Max. Drain Current vs. Case Temperature

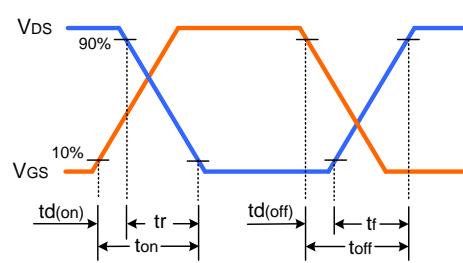
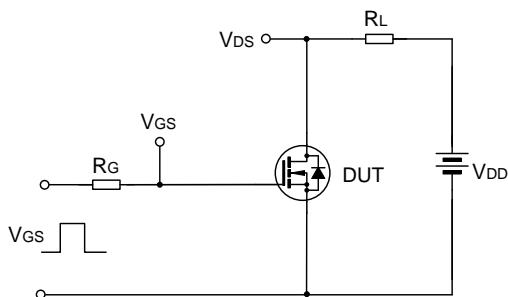




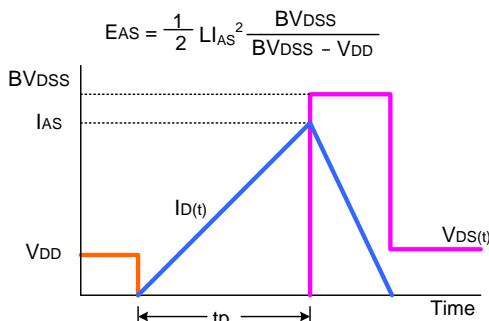
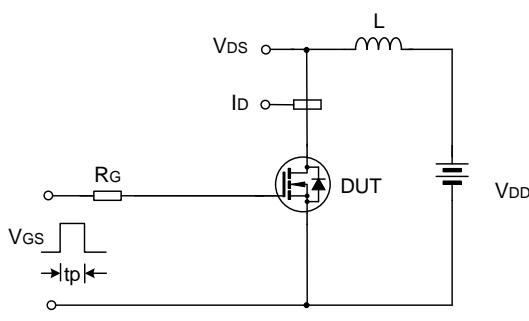
## TYPICAL TEST CIRCUIT



Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



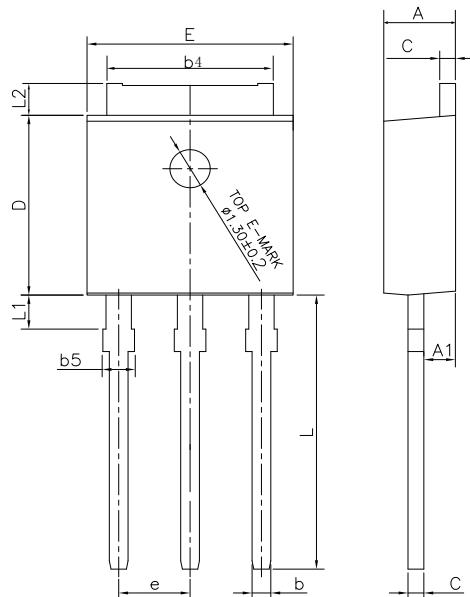
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

TO-251J-3L

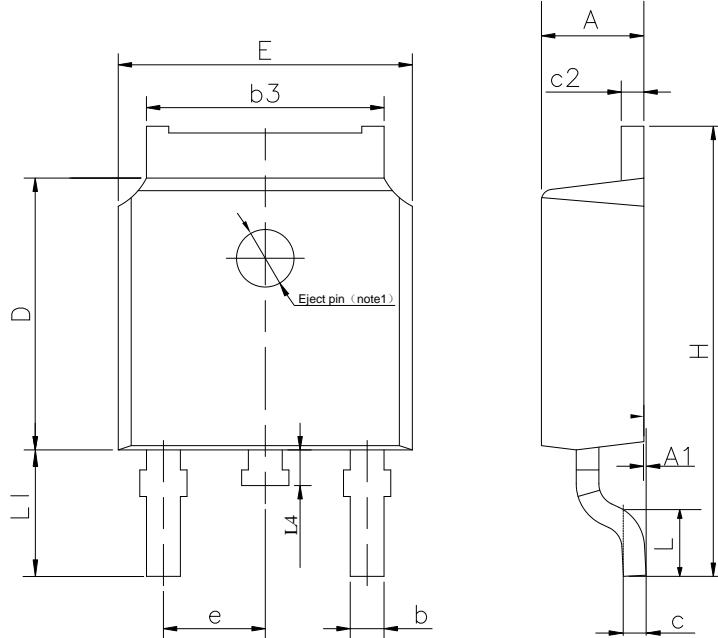
UNIT: mm



SYMBOL	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	---	0.89
b4	4.95	5.33	5.46
b5	---	---	1.05
c	0.46	---	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e		2.29 BCS	
L	8.89	9.30	9.65
L1	0.95	---	1.50
L2	0.89	---	1.27

TO-252-2L

UNIT: mm



SYMBOL	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	---	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	---	0.65
c2	0.45	---	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e		2.30TYP	
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1		2.90REF	
L4	0.60	0.80	1.00

NOTE1 : There are two conditions for this position:has an eject pin or has no eject pin.



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Rev.: **1.2**

Revision History:

1. Modify Electrical schematic and TYPICAL TEST CIRCUIT
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Rev.: **1.1**

Revision History:

1. Add TO-252-2L
- 

Rev.: **1.0**

Revision History:

1. First release
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